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# BFU725F/N1

NPN wideband silicon germanium RF transistor

Rev. 2 — 3 November 2011

Product data sheet

## 1. Product profile

### 1.1 General description

NPN silicon germanium microwave transistor for high speed, low noise applications in a plastic, 4-pin dual-emitter SOT343F package.

#### CAUTION



This device is sensitive to ElectroStatic Discharge (ESD). Observe precautions for handling electrostatic sensitive devices.

Such precautions are described in the *ANSI/ESD S20.20*, *IEC/ST 61340-5*, *JESD625-A* or equivalent standards.

### 1.2 Features and benefits

- Low noise high gain microwave transistor
- Noise figure (NF) = 0.7 dB at 5.8 GHz
- High maximum stable gain 27 dB at 1.8 GHz
- 110 GHz  $f_T$  silicon germanium technology

### 1.3 Applications

- 2nd LNA stage and mixer stage in DBS LNB's
- Satellite radio
- Low noise amplifiers for microwave communications systems
- WLAN and CDMA applications
- Analog/digital cordless applications
- Ka band oscillators (DRO's)

### 1.4 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{CBO}$	collector-base voltage	open emitter	-	-	10	V
$V_{CEO}$	collector-emitter voltage	open base	-	-	2.8	V
$V_{EBO}$	emitter-base voltage	open collector	-	-	1.0	V
$I_C$	collector current		-	25	40	mA
$P_{tot}$	total power dissipation	$T_{sp} \leq 90\text{ }^\circ\text{C}$	<a href="#">1</a>	-	136	mW
$h_{FE}$	DC current gain	$I_C = 10\text{ mA}$ ; $V_{CE} = 2\text{ V}$ ; $T_j = 25\text{ }^\circ\text{C}$	160	280	400	



**Table 1. Quick reference data ...continued**

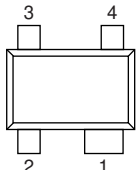
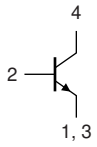
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$C_{CBS}$	collector-base capacitance	$V_{CB} = 2\text{ V}; f = 1\text{ MHz}$	-	70	-	fF
$f_T$	transition frequency	$I_C = 25\text{ mA}; V_{CE} = 2\text{ V}; f = 2\text{ GHz}; T_{amb} = 25\text{ °C}$	-	55	-	GHz
$G_{p(max)}$	maximum power gain	$I_C = 25\text{ mA}; V_{CE} = 2\text{ V}; f = 5.8\text{ GHz}; T_{amb} = 25\text{ °C}$	[2]	18	-	dB
NF	noise figure	$I_C = 5\text{ mA}; V_{CE} = 2\text{ V}; f = 5.8\text{ GHz}; \Gamma_S = \Gamma_{opt}; T_{amb} = 25\text{ °C}$	-	0.7	-	dB

[1]  $T_{sp}$  is the temperature at the solder point of the emitter lead.

[2]  $G_{p(max)}$  is the maximum power gain, if  $K > 1$ . If  $K < 1$  then  $G_{p(max)}$  = Maximum Stable Gain (MSG).

## 2. Pinning information

**Table 2. Discrete pinning**

Pin	Description	Simplified outline	Graphic symbol
1	emitter		
2	base		
3	emitter		
4	collector		

## 3. Ordering information

**Table 3. Ordering information**

Type number	Package		Version
	Name	Description	
BFU725F/N1	-	plastic surface-mounted flat pack package; reverse pinning; 4 leads	SOT343F

## 4. Marking

**Table 4. Marking**

Type number	Marking	Description
BFU725F/N1	B7*	* = p : made in Hong Kong * = t : made in Malaysia * = W : made in China

## 5. Limiting values

**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

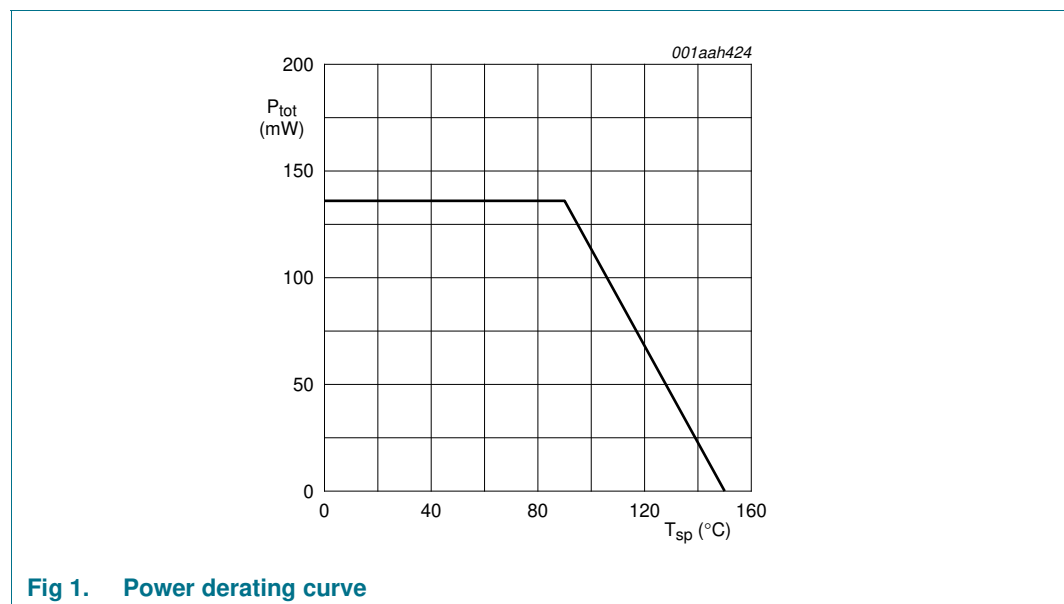
Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CBO}$	collector-base voltage	open emitter	-	10	V
$V_{CEO}$	collector-emitter voltage	open base	-	2.8	V
$V_{EBO}$	emitter-base voltage	open collector	-	1.0	V
$I_C$	collector current		-	40	mA
$P_{tot}$	total power dissipation	$T_{sp} \leq 90\text{ }^\circ\text{C}$	[1]	136	mW
$T_{stg}$	storage temperature		-65	+150	$^\circ\text{C}$
$T_j$	junction temperature		-	150	$^\circ\text{C}$

[1]  $T_{sp}$  is the temperature at the solder point of the emitter lead.

## 6. Thermal characteristics

**Table 6. Thermal characteristics**

Symbol	Parameter	Conditions	Typ	Unit
$R_{th(j-sp)}$	thermal resistance from junction to solder point		440	K/W



**Fig 1. Power derating curve**



## 7. Characteristics

**Table 7. Characteristics**

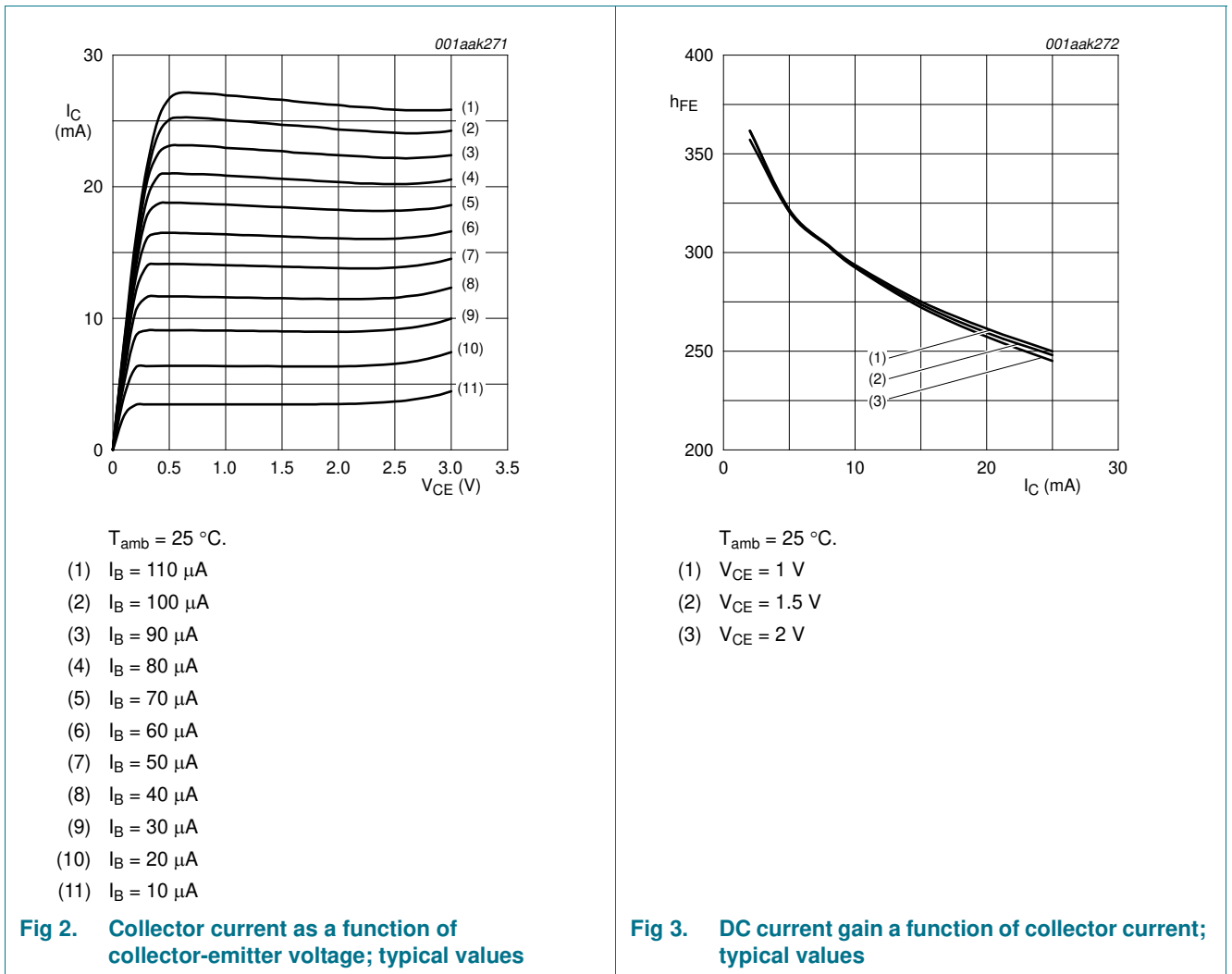
$T_j = 25\text{ °C}$  unless otherwise specified.

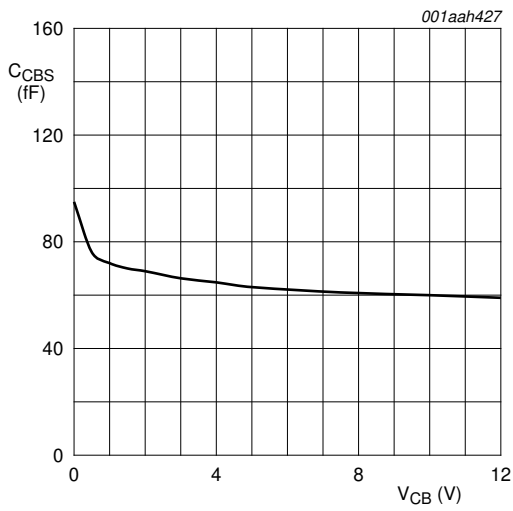
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{(BR)CBO}$	collector-base breakdown voltage	$I_C = 2.5\ \mu\text{A}; I_E = 0\ \text{mA}$	10	-	-	V
$V_{(BR)CEO}$	collector-emitter breakdown voltage	$I_C = 1\ \text{mA}; I_B = 0\ \text{mA}$	2.8	-	-	V
$I_C$	collector current		-	25	40	mA
$I_{CBO}$	collector-base cut-off current	$I_E = 0\ \text{mA}; V_{CB} = 4.5\ \text{V}$	-	-	100	nA
$h_{FE}$	DC current gain	$I_C = 10\ \text{mA}; V_{CE} = 2\ \text{V}$	160	280	400	
$C_{CES}$	collector-emitter capacitance	$V_{CB} = 2\ \text{V}; f = 1\ \text{MHz}$	-	268	-	fF
$C_{EBS}$	emitter-base capacitance	$V_{EB} = 0.5\ \text{V}; f = 1\ \text{MHz}$	-	400	-	fF
$C_{CBS}$	collector-base capacitance	$V_{CB} = 2\ \text{V}; f = 1\ \text{MHz}$	-	70	-	fF
$f_T$	transition frequency	$I_C = 25\ \text{mA}; V_{CE} = 2\ \text{V}; f = 2\ \text{GHz}; T_{amb} = 25\text{ °C}$	-	55	-	GHz
$G_{p(max)}$	maximum power gain	$I_C = 25\ \text{mA}; V_{CE} = 2\ \text{V}; T_{amb} = 25\text{ °C}$	[1]			
		$f = 1.5\ \text{GHz}$	-	28	-	dB
		$f = 1.8\ \text{GHz}$	-	27	-	dB
		$f = 2.4\ \text{GHz}$	-	25.5	-	dB
		$f = 5.8\ \text{GHz}$	-	18	-	dB
		$f = 12\ \text{GHz}$	-	13	-	dB
$ S_{21} ^2$	insertion power gain	$I_C = 25\ \text{mA}; V_{CE} = 2\ \text{V}; T_{amb} = 25\text{ °C}$				
		$f = 1.5\ \text{GHz}$	-	26.7	-	dB
		$f = 1.8\ \text{GHz}$	-	25.4	-	dB
		$f = 2.4\ \text{GHz}$	-	23	-	dB
		$f = 5.8\ \text{GHz}$	-	16	-	dB
		$f = 12\ \text{GHz}$	-	9.3	-	dB
NF	noise figure	$I_C = 5\ \text{mA}; V_{CE} = 2\ \text{V}; \Gamma_S = \Gamma_{opt}; T_{amb} = 25\text{ °C}$				
		$f = 1.5\ \text{GHz}$	-	0.42	-	dB
		$f = 1.8\ \text{GHz}$	-	0.43	-	dB
		$f = 2.4\ \text{GHz}$	-	0.47	-	dB
		$f = 5.8\ \text{GHz}$	-	0.7	-	dB
		$f = 12\ \text{GHz}$	-	1.1	-	dB
$G_{ass}$	associated gain	$I_C = 5\ \text{mA}; V_{CE} = 2\ \text{V}; \Gamma_S = \Gamma_{opt}; T_{amb} = 25\text{ °C}$				
		$f = 1.5\ \text{GHz}$	-	24	-	dB
		$f = 1.8\ \text{GHz}$	-	22	-	dB
		$f = 2.4\ \text{GHz}$	-	20	-	dB
		$f = 5.8\ \text{GHz}$	-	13.5	-	dB
		$f = 12\ \text{GHz}$	-	10	-	dB

**Table 7. Characteristics ...continued**  
 $T_j = 25\text{ }^\circ\text{C}$  unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$P_{L(1dB)}$	output power at 1 dB gain compression	$I_C = 25\text{ mA}; V_{CE} = 2\text{ V}; Z_S = Z_L = 50\text{ }\Omega; T_{amb} = 25\text{ }^\circ\text{C}$				
		$f = 1.5\text{ GHz}$	-	8.5	-	dBm
		$f = 1.8\text{ GHz}$	-	9	-	dBm
		$f = 2.4\text{ GHz}$	-	8.5	-	dBm
IP3	third-order intercept point	$I_C = 25\text{ mA}; V_{CE} = 2\text{ V}; Z_S = Z_L = 50\text{ }\Omega; T_{amb} = 25\text{ }^\circ\text{C}; f_2 = f_1 + 1\text{ MHz}$				
		$f_1 = 1.5\text{ GHz}$	-	17	-	dBm
		$f_1 = 1.8\text{ GHz}$	-	17	-	dBm
		$f_1 = 2.4\text{ GHz}$	-	17	-	dBm
		$f_1 = 5.8\text{ GHz}$	-	19	-	dBm

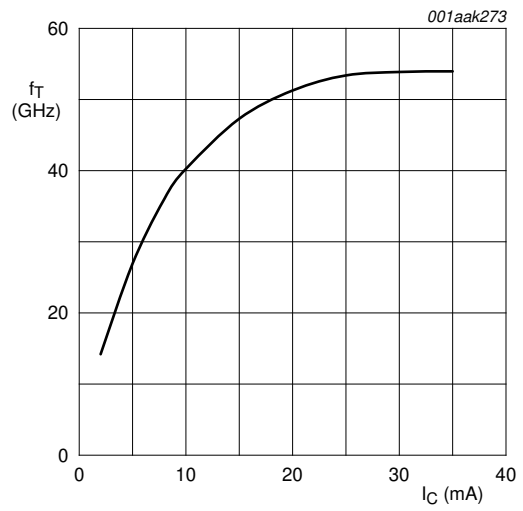
[1]  $G_{p(max)}$  is the maximum power gain, if  $K > 1$ . If  $K < 1$  then  $G_{p(max)} = \text{MSG}$ .





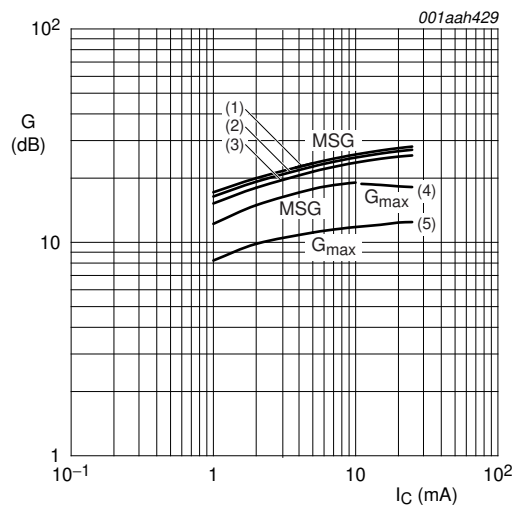
$f = 1 \text{ MHz}$ ,  $T_{\text{amb}} = 25 \text{ }^\circ\text{C}$ .

**Fig 4. Collector-base capacitance as a function of collector-base voltage; typical values**



$V_{\text{CE}} = 2 \text{ V}$ ;  $f = 2 \text{ GHz}$ ;  $T_{\text{amb}} = 25 \text{ }^\circ\text{C}$ .

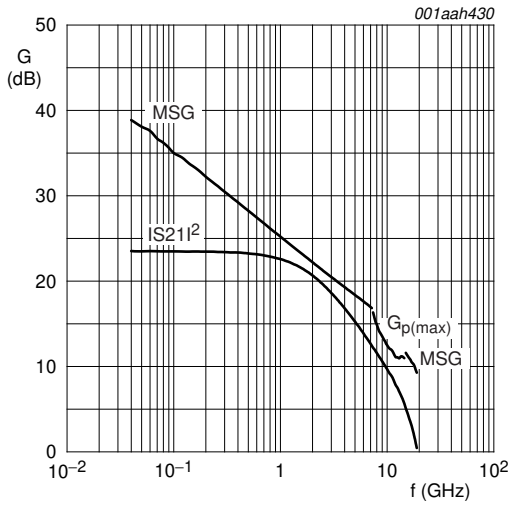
**Fig 5. Transition frequency as a function of collector current; typical values**



$V_{\text{CE}} = 2 \text{ V}$ ;  $T_{\text{amb}} = 25 \text{ }^\circ\text{C}$ .

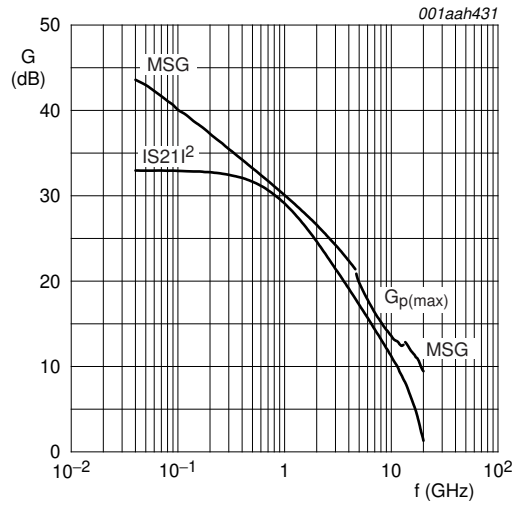
- (1)  $f = 1.5 \text{ GHz}$
- (2)  $f = 1.8 \text{ GHz}$
- (3)  $f = 2.4 \text{ GHz}$
- (4)  $f = 5.8 \text{ GHz}$
- (5)  $f = 12 \text{ GHz}$

**Fig 6. Gain as a function of collector current; typical value**



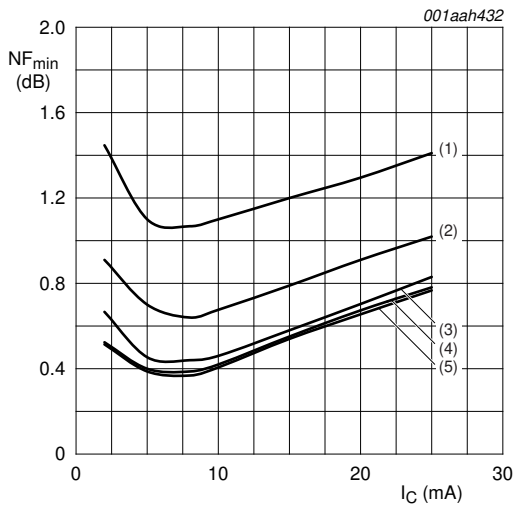
$V_{CE} = 2\text{ V}; I_C = 5\text{ mA}; T_{amb} = 25\text{ }^\circ\text{C}.$

**Fig 7. Gain as a function of frequency; typical values**



$V_{CE} = 2\text{ V}; I_C = 25\text{ mA}; T_{amb} = 25\text{ }^\circ\text{C}.$

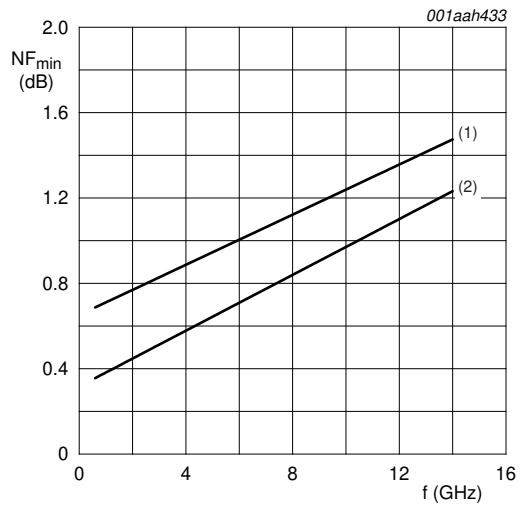
**Fig 8. Gain as a function of frequency; typical values**



$V_{CE} = 2\text{ V}; T_{amb} = 25\text{ }^\circ\text{C}.$

- (1)  $f = 12\text{ GHz}$
- (2)  $f = 5.8\text{ GHz}$
- (3)  $f = 2.4\text{ GHz}$
- (4)  $f = 1.8\text{ GHz}$
- (5)  $f = 1.5\text{ GHz}$

**Fig 9. Minimum noise figure as a function of collector current; typical values**



$V_{CE} = 2\text{ V}; T_{amb} = 25\text{ }^\circ\text{C}.$

- (1)  $I_C = 25\text{ mA}$
- (2)  $I_C = 5\text{ mA}$

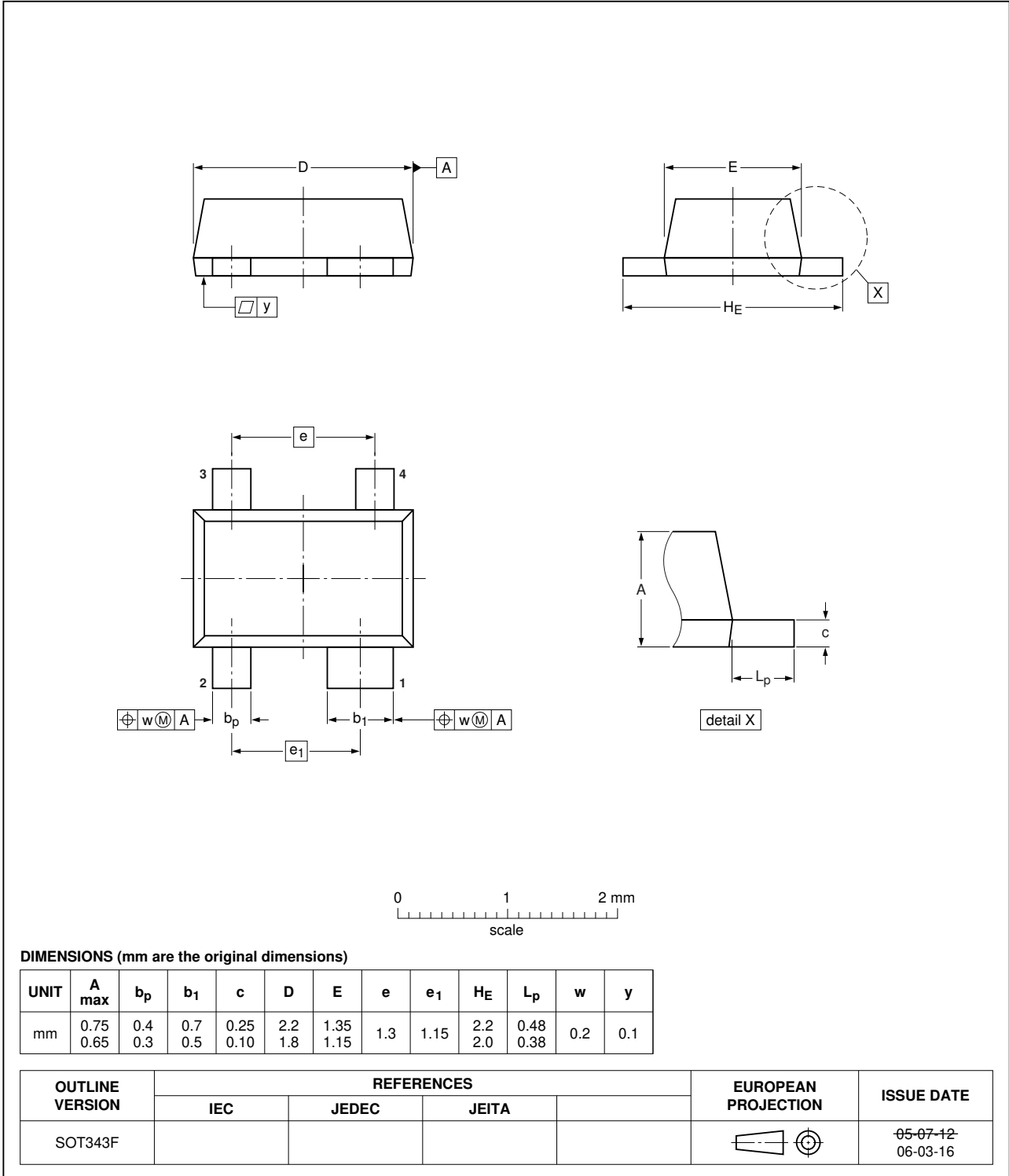
**Fig 10. Minimum noise figure as a function of frequency; typical values**



**8. Package outline**

Plastic surface-mounted flat pack package; reverse pinning; 4 leads

SOT343F



**Fig 11. Package outline SOT343F**

## 9. Abbreviations

**Table 8. Abbreviations**

Acronym	Description
CDMA	Code Division Multiple Access
DBS	Direct Broadcast Satellite
DC	Direct Current
DRO	Dielectric Resonator Oscillator
LNA	Low Noise Amplifier
LNB	Low Noise Block
Ka	Kurtz above
NPN	Negative-Positive-Negative
RF	Radio Frequency
WLAN	Wireless Local Area Network

## 10. Revision history

**Table 9. Revision history**

Document ID	Release date	Data sheet status	Change notice	Supersedes
BFU725F_N1 v.2	20111103	Product data sheet	-	BFU725F_N1 v.1
Modifications:	<ul style="list-style-type: none"> <li>• <a href="#">Table 1 on page 1</a>: The maximum value for <math>V_{EBO}</math> has been changed to 1.0 V.</li> <li>• <a href="#">Table 5 on page 3</a>: The maximum value for <math>V_{EBO}</math> has been changed to 1.0 V.</li> </ul>			
BFU725F_N1 v.1	20090713	Product data sheet	-	-

## 11. Legal information

### 11.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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